

## WPMD2011

Dual P-Channel -20V, -4.4A, 52mΩ Power MOSFET

[Http://www.willsemi.com](http://www.willsemi.com)

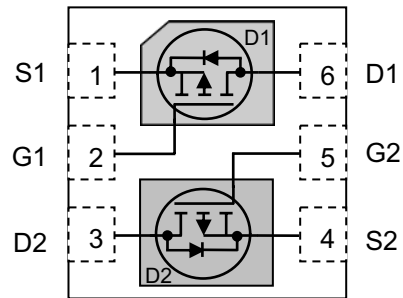
$V_{(BR)DSS}$	$R_{ds(on)}$ ( $\Omega$ )
-20	0.052 @ -4.5V
	0.064 @ -2.5V
	0.080 @ -1.8V
	0.090 @ -1.5V



**DFN2x2-6L**

### Description

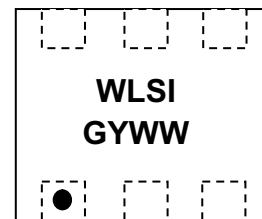
The WPMD2011 is P-Channel enhancement dual MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in DC-DC conversion and power switch applications. Standard Product WPMD2011 is Pb-free.



**Pin Configuration (Top View)**

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for highest DC current
- Extremely low threshold voltage
- Bidirectional current flow with common source configuration
- DFN2x2 package provides exposed drain pad for excellent thermal conduction



**WLSI** = Company Code  
**G** = Device Code  
**Y** = Year (last digit)  
**WW** = Week

### Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power switch
- High side load switch
- Battery management and charging circuit

### Order Information

Device	Package	Shipping
WPMD2011-6/TR	DFN2x2-6L	3000/Tape&Reel

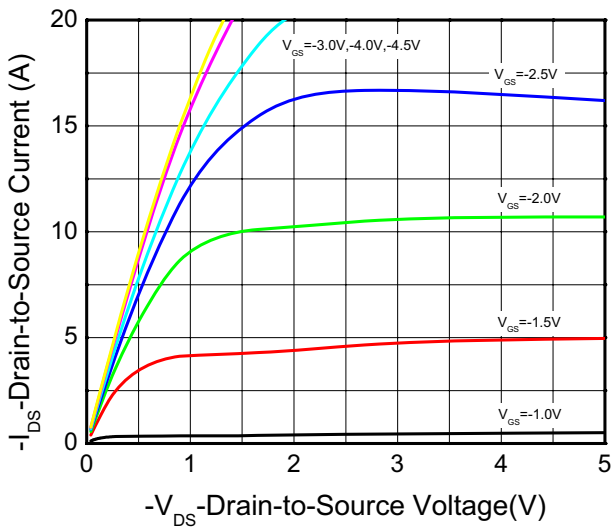
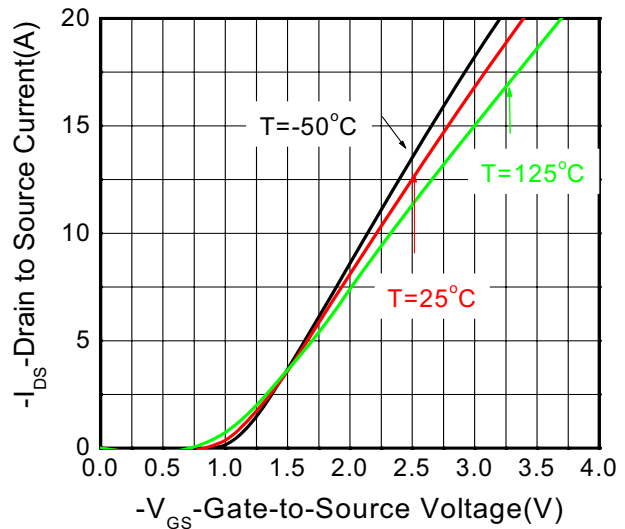
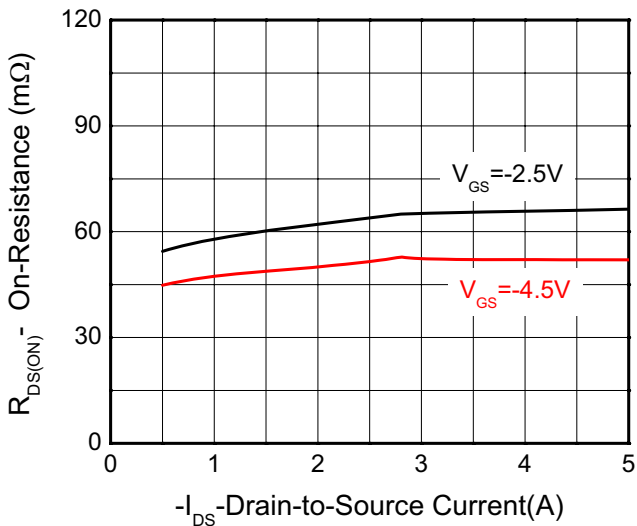
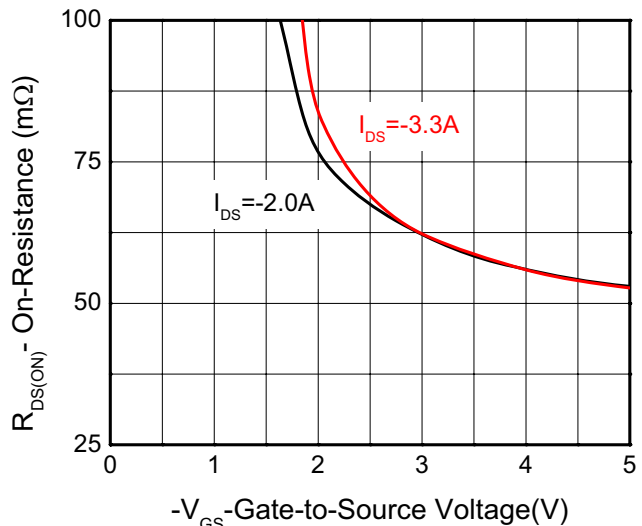
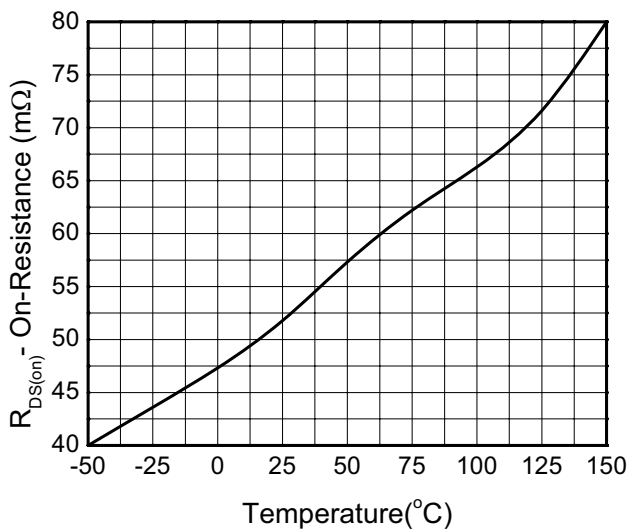
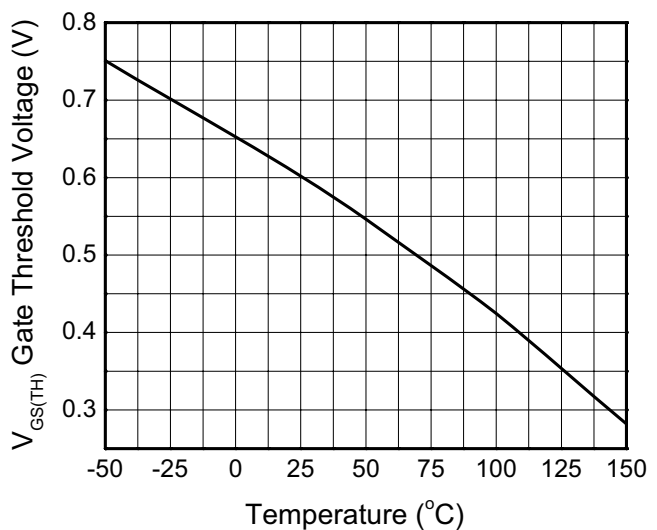
<b>ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C, unless otherwise noted)</b>					
Parameter		Symbol	10S	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	-20		V
Gate-Source Voltage		$V_{GS}$	$\pm 12$		
Continuous Drain Current ( $T_J = 150\text{ °C}$ ) <sup>a</sup>	$T_A = 25\text{ °C}$	$I_D$	-4.4	-3.7	A
	$T_A = 70\text{ °C}$		-3.5	-3.0	
Maximum Power Dissipation <sup>a</sup>	$T_A = 25\text{ °C}$	$P_D$	2.0	1.4	W
	$T_A = 70\text{ °C}$		1.3	0.9	
Continuous Drain Current ( $T_J = 150\text{ °C}$ ) <sup>b</sup>	$T_A = 25\text{ °C}$	$I_D$	-3.2	-2.6	A
	$T_A = 70\text{ °C}$		-2.5	-2.1	
Maximum Power Dissipation <sup>b</sup>	$T_A = 25\text{ °C}$	$P_D$	1.0	0.7	W
	$T_A = 70\text{ °C}$		0.6	0.4	
Pulsed Drain Current <sup>c</sup>		$I_{DM}$	-15		A
Operating Junction Temperature		$T_J$	150		°C
Storage Temperature		$T_{stg}$	-55 to 150		°C

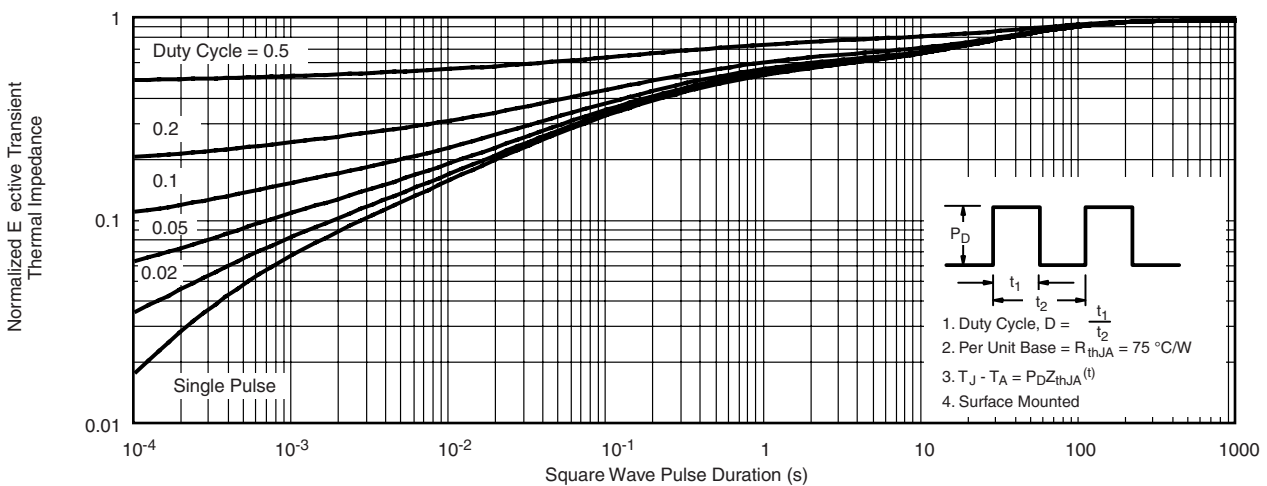
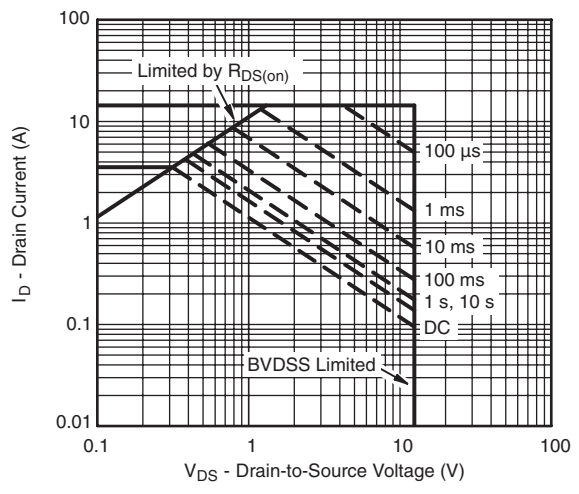
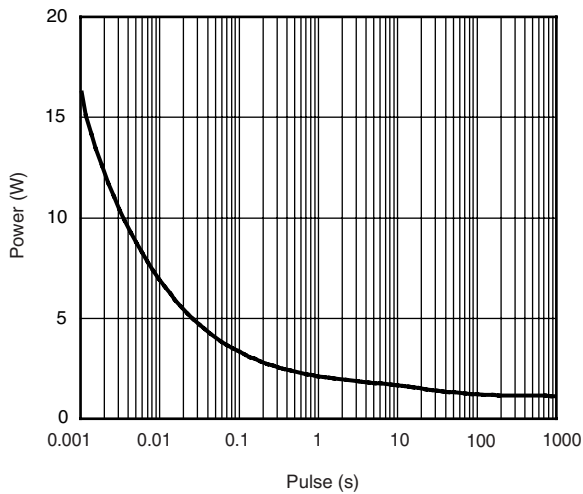
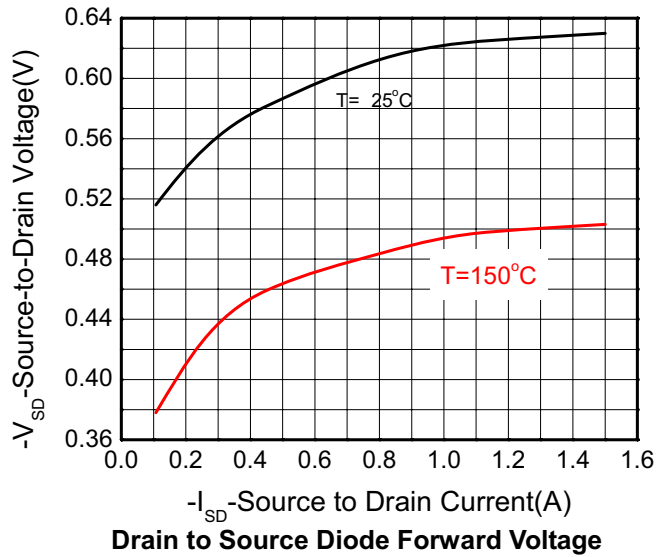
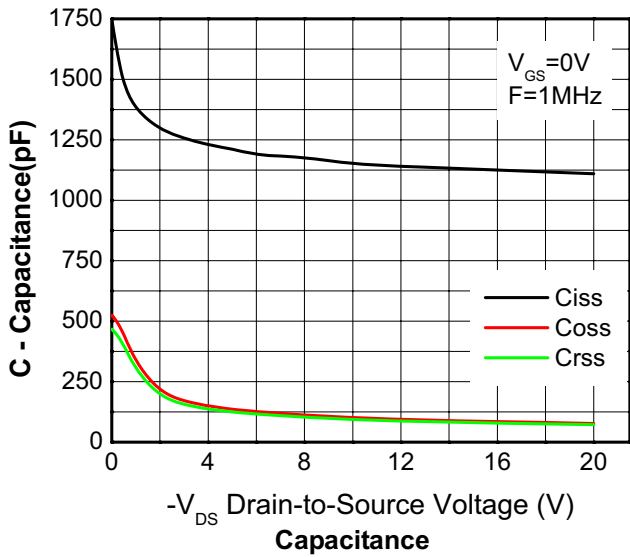
<b>THERMAL RESISTANCE RATINGS</b>					
<b>Single Operation</b>					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	45	60	°C/W
	Steady State		62	85	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	80	115	
	Steady State		120	170	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	32	40	
<b>Dual operation</b>					
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	40	55	°C/W
	Steady State		58	80	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	75	110	
	Steady State		115	160	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	30	36	

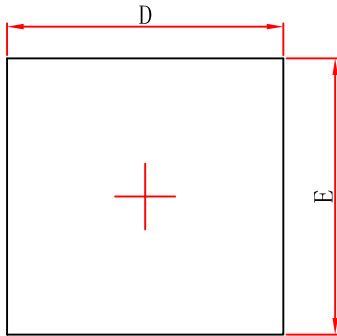
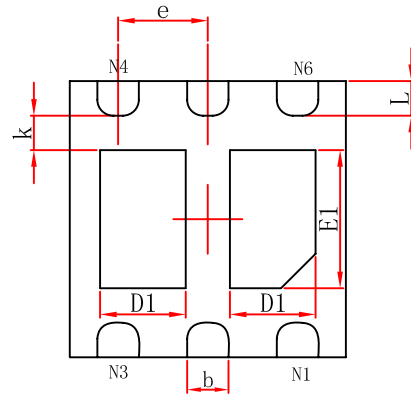
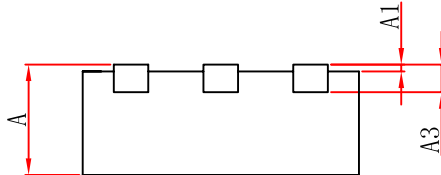
- Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- Repetitive rating, pulse width limited by junction temperature,  $t_p = 10\mu\text{s}$ , Duty Cycle=1%
- Repetitive rating, pulse width limited by junction temperature  $T_J(\text{MAX}) = 150\text{ °C}$

**Electrical Characteristics** (Ta= 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
Gate-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\text{ }\mu\text{A}$	-0.35	-0.6	-1.0	V
Drain-Source On Resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -4.0\text{ A}$		52	70	m $\Omega$
		$V_{GS} = -2.5\text{ V}, I_D = -3.0\text{ A}$		64	85	
		$V_{GS} = -1.8\text{ V}, I_D = -2.0\text{ A}$		80	100	
		$V_{GS} = -1.5\text{ V}, I_D = -1.0\text{ A}$		90	150	
Forward Transconductance	$g_{FS}$	$V_{DS} = -5\text{ V}, I_D = -3.6\text{ A}$		10		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz},$ $V_{DS} = -10\text{ V}$		1130		pF
Output Capacitance	$C_{OSS}$			120		
Reverse Transfer Capacitance	$C_{RSS}$			115		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V}, V_{DS} = -10\text{ V},$ $I_D = -2.7\text{ A}$		11		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.6		
Gate-Source Charge	$Q_{GS}$			1.3		
Gate-Drain Charge	$Q_{GD}$			2.7		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$td_{(ON)}$	$V_{GS} = -4.5\text{ V}, V_{DS} = -6\text{ V},$ $R_L = 3\text{ }\Omega, R_G = 6\text{ }\Omega$		9.5		ns
Rise Time	$tr$			5.8		
Turn-Off Delay Time	$td_{(OFF)}$			54		
Fall Time	$tf$			13		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Recovery Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = -1.0\text{ A}$		-0.62	-1.5	V

**Typical Performance Characteristics**

**Output Characteristics**

**Transfer Characteristics**

**ON Resistance vs. Drain Current**

**ON Resistance vs. Gate to Source Voltage**

**ON Resistance vs. Junction Temperature**

**Threshold Voltage vs. Temperature**



**Packaging Information**
**DFN2x2-6L**

**Top View**

**Bottom View**

**Side View**

Symbol	Dimension in Millimeters	
	Min.	Max.
A	0.700	0.800
A1	0.000	0.050
A3	0.203REF	
D	1.900	2.100
E	1.900	2.100
E1	0.750	0.850
D1	0.600	0.700
k	0.200MIN	
b	0.250	0.350
e	0.650TYP	
L	0.250	0.350